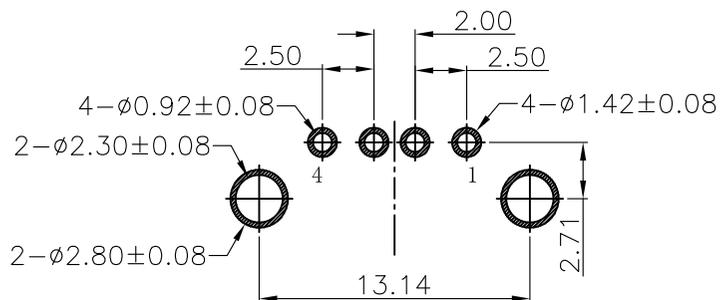
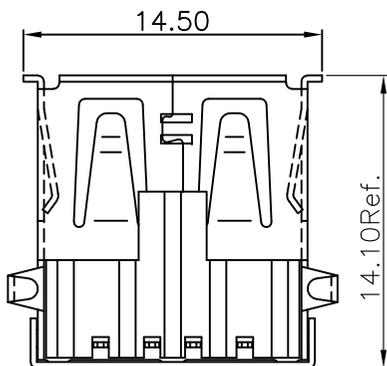


# GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2018/04/24	Phebe Su
A1			Change & Add	2023/07/23	Ken Lin



RECOMMENDED PCB LAYOUT(TOP VIEW)

GENERAL TOLERANCES:±0.05



**NOTE:**

**1. Material:**

Housing: LCP,White,Thermoplastics,UL94V-0(Halogen Free)

Contact: C7025

Shell: SUS301

**2. Finish:**

Contact: Gold Flash (0.8u" Min.) Plated on Contact Area,  
80u" Min.Tin Plated on Solder Tails Area,  
50u" Min.Nickel Underplating Over All.

Shell: 50u" Min.Nickel Underplating Over All.

**3. Specification:**

3.1: Rated current: 1.5 A

Insulation Resistance:

1000MΩ Min. at 500V/DC for 1Minute.

Withstanding voltage: 500 VAC/minute

Contact Resistance: 30 m ohms Max.

3.2: MECHANICAL

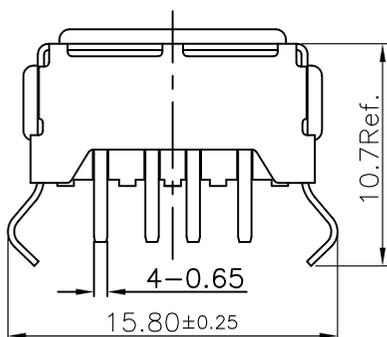
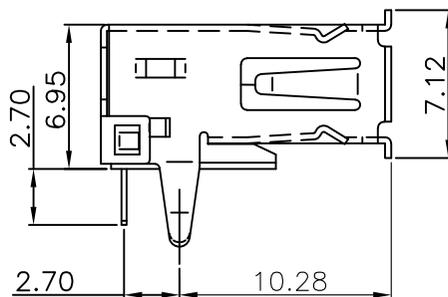
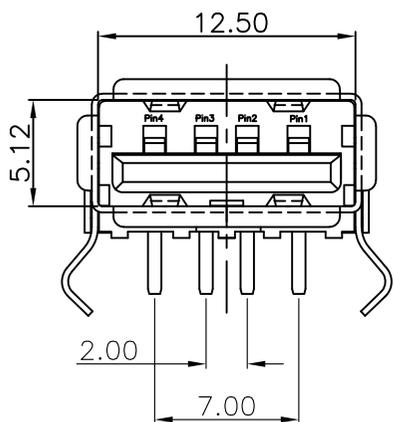
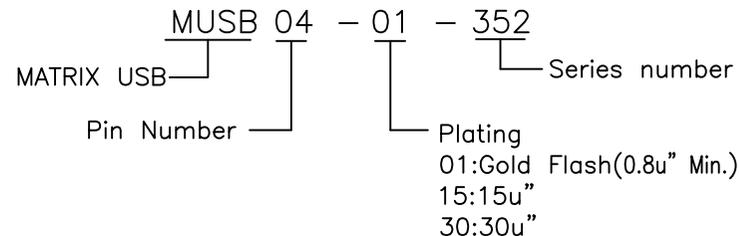
Mating force: 35N Max.

Unmating force: 10N Min.

Durability: 1500 cycles Min.

3.3: OPERATING TEMPERATURE: -55°C+85°C

MATRIX PART NO:



PIN NO.	PIN 1	PIN 2	PIN 3	PIN 4
SLGNAL NAME	V BUS	D-	D+	GND

Matrix Electronics Co.,Ltd				
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 ANGLE: ±3	DESIGN BY : Ken Lin	DATE : 2023/07/23	PART NAME: USB AF R/A DIP TYPE REVERSE	
	CHECKED BY: Vicky Hsieh	DATE : 2023/07/23	PART NO.	MUSB04-01-352
	APPROVED BY1: Richard Hsieh	DATE : 2023/07/23	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2023/07/23	DRAW NO.	
UNIT: mm [inch] SCALE:1:1 SIZE:A4			SHEET NO.	1 OF 1